



EKC525™ Cu

EKC Copper Integration Technology

Product Description

EKC525™ Cu is an advanced formulation specifically designed for the removal of copper-containing residues in the presence of exposed copper and low-k dielectrics.

Applications

EKC525™ Cu is designed for use at the cutting edge of advanced interconnect, in damascene and dual damascene architectures, where Cu is employed as the interconnect metal.

Product Performance

EKC525™ Cu completely removes Cu residues created at the end of a dielectric etch step. Used under mild conditions for relatively short times, EKC525™ Cu is completely benign towards copper.

"Complete removal of copper containing residues, retaining metal integrity"

Cu TEM Images

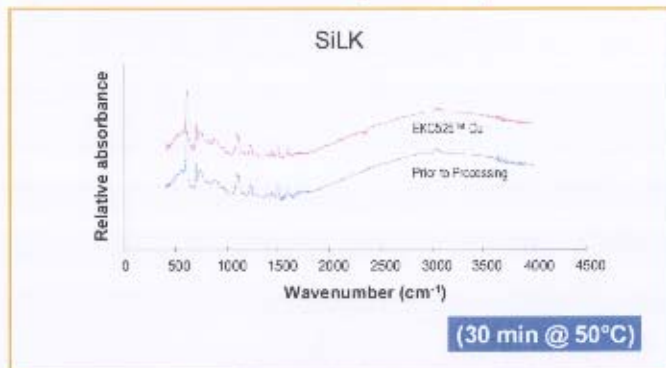


before



after

Excellent organic low-k dielectric compatibility



Cleaning Results (Cu/Si_xN_y/TEOS)

Before Processing



After EKC525™ Cu



(15 min @ 50°C; H₂O Rinse)

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WWW.EKCTECH.COM

EKC Technology

1320 El Capitan Drive, 4th Floor

Danville, CA 94526

tel. +1 (510) 784 9105 facs. +1 (925) 973 1002

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